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(54) MANUFACTURE OF POLYIMIDE BASE PLATE

(57)Abstract:

PURPOSE: To obtain a method for preparation of a polyimide base plate which enables preparation of a printed wiring board of high reliability, a flexible printed circuit and an automatic bonding tape and which has a large strength of adhesion between an electroless plating film and an electrolytic plating film.

CONSTITUTION: In a manufacturing method of a polyimide base plate having a conductive film provided on one or both surfaces of polyimide resin, a conductive thin film of a thickness 10 μ m or below or preferably 5 μ m or below is provided on the surface of the polyimide resin and then subjected to heat treatment of 300 to 500°C in an inactive atmosphere. Subsequently, the surface of the conductive film is washed with a solution containing at least one kind of ions of hypochlorite, chlorite and perchlorate and then the surface of the conductive thin film is subjected further to electroplating, whereby the conductive film is formed.

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